ABSTRACT

Disclosed herein are an anisotropically conductive connector, by which positioning, and holding and fixing to a wafer can be conducted with ease even when the wafer has a large area of 8 inches or greater in diameter, and the pitch of electrodes to be inspected is small, and good conductivity is retained even upon repeated use, and applications thereof. The anisotropically conductive connector has a frame plate, in which a plurality of anisotropically conductive film-arranging holes have been formed correspondingly to electrode regions in all or part of integrated circuits on a wafer, and a plurality of elastic anisotropically conductive films arranged in the respective anisotropically conductive film-arranging holes. The elastic anisotropically conductive films each have a plurality of conductive parts for connection extending in a thickness-wise direction thereof and containing conductive particles, and an insulating part mutually insulating them. The conductive particles are obtained by coating core particles exhibiting magnetism with a high-conductive metal, a proportion of the high-conductive metal to the core particles is at least 15 % by mass, and the following t is at least 50 nm: $t = [1/(Sw \cdot \rho)] \times [N/(1 - N)]$, wherein Sw is a BET specific surface area (m^2/kg) of the core particles, ρ is a specific gravity (kg/m^3) of the high-conductive metal, and N is (mass of the high-conductive metal/total mass of the conductive particles).